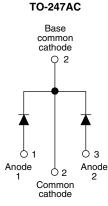


Vishay Semiconductors

HEXFRED[®] Ultrafast Soft Recovery Diode, 2 x 8 A





PRODUCT SUMMARY								
Package	TO-247AC							
I _{F(AV)}	2 x 8 A							
V _R	1200 V							
V _F at I _F	2.4 V							
t _{rr} typ.	28 ns							
T _J max.	150 °C							
Diode variation	Single die							

FEATURES

- Ultrafast and ultrasoft recovery
- Very low I_{RRM} and Q_{rr}
- Designed and qualified according to JEDEC[®]-JESD47
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

BENEFITS

- Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

VS-HFA16PA120C... is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 1200 V and 8 A per leg continuous current, the VS-HFA16PA120C... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to "snap-off" during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA16PA120C... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Cathode to anode voltage	V _R		1200	V					
Maximum continuous forward current	I_	T _C = 100 °C	8						
per device	e I _F	$1_{\rm C} = 100$ C	16	А					
Single pulse forward current	I _{FSM}		130	A					
Maximum repetitive forward current	I _{FRM}		32						
Maximum newer discinction	D-	T _C = 25 °C	73.5	W					
Maximum power dissipation	PD	T _C = 100 °C	29	٧V					
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +150	°C					

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RoHS

COMPLIANT

HALOGEN

FREE

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ELECTRICAL SPECIFICATIONS PER LEG ($T_J = 25 \text{ °C}$ unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 μA	1200	-	-				
Maximum forward voltage		I _F = 8.0 A	-	2.6	3.3	v			
	V_{FM}	I _F = 16 A	-	3.4	4.3				
		I _F = 8.0 A, T _J = 125 °C	-	2.4	3.1				
Maximum reverse		$V_{R} = V_{R}$ rated	-	0.31	10				
leakage current	I _{RM}	$T_J = 125 \text{ °C}, V_R = 0.8 \text{ x } V_R \text{ rated}$	- 135 1000		μA				
Junction capacitance	CT	V _R = 200 V	-	11	20	pF			
Series inductance	L _S	Measured lead to lead 5 mm from package	-	8.0	-	nH			

DYNAMIC RECOVERY CHARACTERISTICS PER LEG ($T_J = 25$ °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS		
Reverse recovery time	t _{rr}	$I_F = 1.0 \text{ A}, \text{ d}I_F/\text{d}t = 200$) A/µs, V _R = 30 V	-	28	-	ns		
	t _{rr1}	T _J = 25 °C		-	63	95			
	t _{rr2}	T _J = 125 °C		-	106	160			
Peak recovery current	I _{RRM1}	T _J = 25 °C	I _F = 8.0 A dI _F /dt = 200 A/μs V _R = 200 V	-	4.5	8.0	- A nC - Α/μs		
Feak recovery current	I _{RRM2}	T _J = 125 °C		-	6.2	11			
	Q _{rr1}	T _J = 25 °C		-	140	380			
Reverse recovery charge	Q _{rr2}	T _J = 125 °C		-	335	880			
Peak rate of recovery current during $t_{\rm b}$	dl _{(rec)M} /dt1	T _J = 25 °C		-	133	-			
	dl _{(rec)M} /dt2	T _J = 125 °C		-	85	-			

THERMAL - MECHANICAL SPECIFICATIONS										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C				
Thermal resistance, junction to case	R _{thJC}		-	-	1.7					
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	40	K/W				
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.25	-					
Weight			-	6.0	-	g				
weight			-	0.21	-	oz.				
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)				
Marking device		Case style TO-247AC (JEDEC)	HFA16PA120C							

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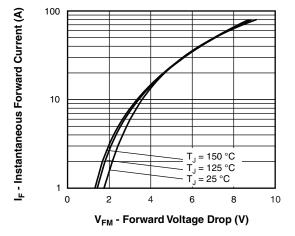


Fig. 1 - Maximum Forward Voltage Drop Characteristics

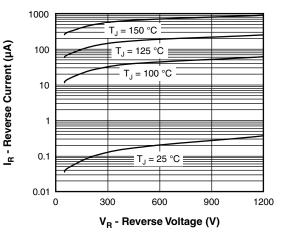


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

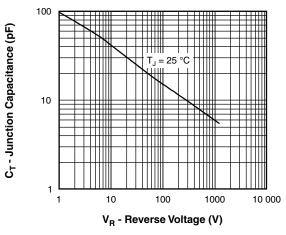


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

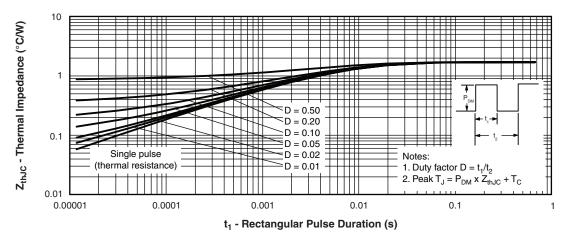


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics



I_{rr} (A)

VS-HFA16PA120CPbF, VS-HFA16PA120C-N3

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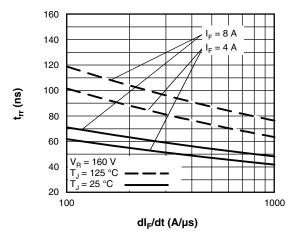


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt

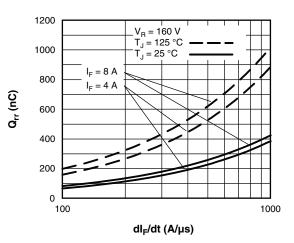


Fig. 7 - Typical Stored Charge vs. dl_F/dt

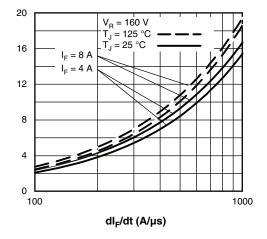


Fig. 6 - Typical Recovery Current vs. dl_F/dt

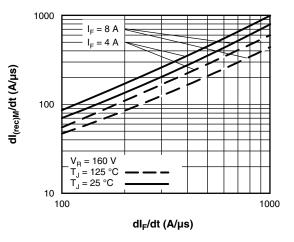


Fig. 8 - Typical dl_{(rec)M}/dt vs. dl_F/dt



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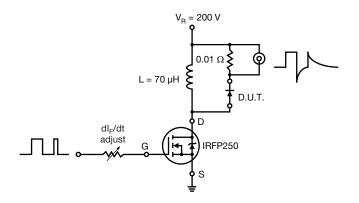


Fig. 9 - Reverse Recovery Parameter Test Circuit

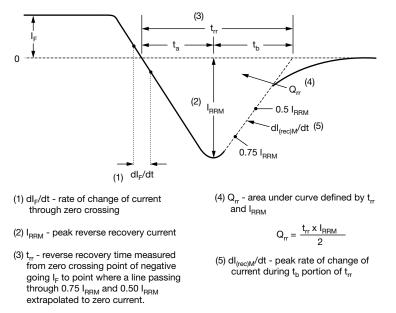
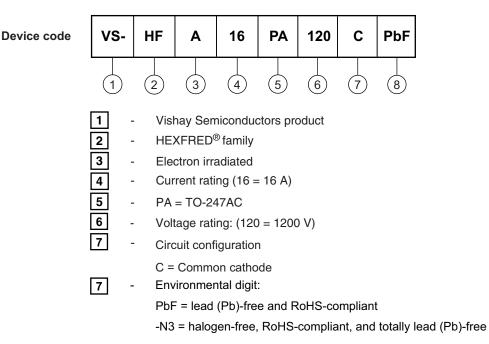


Fig. 10 - Reverse Recovery Waveform and Definitions



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ORDERING INFORMATION TABLE



ORDERING INFORMATION (Example)									
PREFERRED P/N	ERRED P/N QUANTITY PER T/R MINIMUM ORDER QUANTITY PACK/								
VS-HFA16PA120CPbF	25	500	Antistatic plastic tube						
VS-HFA16PA120C-N3	25	500	Antistatic plastic tube						

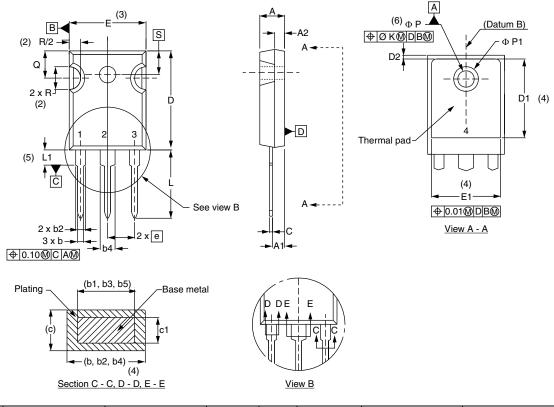
LINKS TO RELATED DOCUMENTS							
Dimensions		www.vishay.com/doc?95542					
Part marking information	TO-247ACPbF	www.vishay.com/doc?95226					
	TO-247AC-N3	www.vishay.com/doc?95007					





TO-247AC - 50 mils L/F

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	INCHES		NOTES	SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STNIBOL	MIN.	MAX.	MIN.	MAX.	NOTES	NOTES	STWBOL	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.65	5.31	0.183	0.209			D2	0.51	1.35	0.020	0.053	
A1	2.21	2.59	0.087	0.102			E	15.29	15.87	0.602	0.625	3
A2	1.17	1.37	0.046	0.054			E1	13.46	-	0.53	-	
b	0.99	1.40	0.039	0.055			e	5.46	BSC	0.215	BSC	
b1	0.99	1.35	0.039	0.053			ØК	0.2	254	0.0)10	
b2	1.65	2.39	0.065	0.094			L	14.20	16.10	0.559	0.634	
b3	1.65	2.34	0.065	0.092			L1	3.71	4.29	0.146	0.169	
b4	2.59	3.43	0.102	0.135			ØР	3.56	3.66	0.14	0.144	
b5	2.59	3.38	0.102	0.133			Ø P1	-	7.39	-	0.291	
С	0.38	0.89	0.015	0.035			Q	5.31	5.69	0.209	0.224	
c1	0.38	0.84	0.015	0.033			R	4.52	5.49	0.178	0.216	
D	19.71	20.70	0.776	0.815	3		S	5.51	BSC	0.217	BSC	
D1	13.08	-	0.515	-	4							

Notes

⁽¹⁾ Dimensioning and tolerancing per ASME Y14.5M-1994

(2) Contour of slot optional

(3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

⁽⁴⁾ Thermal pad contour optional with dimensions D1 and E1

⁽⁵⁾ Lead finish uncontrolled in L1

⁽⁶⁾ Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")

⁽⁷⁾ Outline conforms to JEDEC[®] outline TO-247 with exception of dimension c and Q

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